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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea7n2f40c1

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Electrical Characteristics Page 3

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Symbol	Description	Minimum	Maximum	Unit
V _{CCD_FPLL}	PLL digital power supply	-0.5	1.8	V
V _{CCA_FPLL}	PLL analog power supply	-0.5	3.4	V
V _I	DC input voltage	-0.5	3.8	V
T _J	Operating junction temperature	-55	125	°C
T _{STG}	Storage temperature (No bias)	-65	150	°C
I _{OUT}	DC output current per pin	-25	40	mA

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left side)	GX, GS, GT	-0.5	3.75	V
V _{CCA_GXBR}	Transceiver channel PLL power supply (right side)	GX, GS	-0.5	3.75	V
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	-0.5	3.75	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCHIP_R}	Transceiver hard IP power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V _{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V _{CCL_GTBR}	Transmitter clock network power supply (right side)	GT	-0.5	1.35	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	-0.5	1.8	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	-0.5	1.8	V

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Page 8 Electrical Characteristics

Table 8 shows the transceiver power supply voltage requirements for various conditions.

Table 8. Transceiver Power Supply Voltage Requirements

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB (2)	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true:					
■ Data rate > 10.3 Gbps.	All	1.05			
■ DFE is used.					
If ANY of the following conditions are true ⁽¹⁾ :			3.0		
ATX PLL is used.					
■ Data rate > 6.5Gbps.	All	1.0			
■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.				1.5	V
If ALL of the following	C1, C2, I2, and I3YY	0.90	2.5		
conditions are true: ATX PLL is not used.					
■ Data rate ≤ 6.5Gbps.	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		
DFE, AEQ, and EyeQ are not used.					

Notes to Table 8:

- (1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.
- (2) If the VCCR_GXB and VCCT_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR_GXB and VCCT_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

DC Characteristics

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

Supply Current

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Electrical Characteristics Page 13

Internal Weak Pull-Up Resistor

Table 16 lists the weak pull-up resistor values for Stratix V devices.

Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices (1), (2)

Symbol	Description	V _{CC10} Conditions (V) ⁽³⁾	Value ⁽⁴⁾	Unit
		3.0 ±5%	25	kΩ
		2.5 ±5%	25	kΩ
	Value of the I/O pin pull-up resistor before	1.8 ±5%	25	kΩ
R _{PU}	and during configuration, as well as user mode if you enable the programmable	1.5 ±5%	25	kΩ
	pull-up resistor option.	1.35 ±5%	25	kΩ
		1.25 ±5%	25	kΩ
		1.2 ±5%	25	kΩ

Notes to Table 16:

- (1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 k Ω .
- (3) The pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO} .
- (4) These specifications are valid with a ±10% tolerance to cover changes over PVT.

I/O Standard Specifications

Table 17 through Table 22 list the input voltage (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL} , respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to "Glossary" on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012_486.

Table 17. Single-Ended I/O Standards for Stratix V Devices

1/0		V _{CCIO} (V)		VII	_(V)	V _{IH}	(V)	V _{OL} (V)	V _{OH} (V)	I _{OL}	I _{OH}
Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Max Min (mA)		(mA)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V _{CCIO} - 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.45	V _{CCIO} – 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.25 * V _{CCIO}	0.75 * V _{CCIO}	2	-2
1.2 V	1.14	1.2	1.26	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.25 * V _{CCIO}	0.75 * V _{CCIO}	2	-2

Page 18 Switching Characteristics

Switching Characteristics

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as "Preliminary."
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

Transceiver Performance Specifications

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 1 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trar	sceive Grade	r Speed 2	Tran	sceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reference Clock											
Supported I/O Standards	Dedicated reference clock pin	1.2-V	PCML,	1.4-V PCM	L, 1.5-V		2.5-V PCM HCSL	IL, Diffe	rential	LVPECL, L\	DS, and
Sidiludius	RX reference clock pin			1.4-V PCMI	_, 1.5-V	PCML,	2.5-V PCM	L, LVPE	CL, and	d LVDS	
Input Reference Clock Frequency (CMU PLL) (8)	_	40	—	710	40		710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) ⁽⁸⁾	_	100		710	100		710	100	_	710	MHz
Rise time	Measure at ±60 mV of differential signal ⁽²⁶⁾	_	_	400	_		400	_	_	400	ne
Fall time	Measure at ±60 mV of differential signal ⁽²⁶⁾	—	—	400	_	_	400	_	_	400	ps
Duty cycle	_	45	_	55	45	_	55	45	_	55	%
Spread-spectrum modulating clock frequency	PCI Express® (PCIe®)	30	_	33	30		33	30	_	33	kHz

Switching Characteristics Page 19

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (21)	_	_	100	_	_	100	_	_	100	_	Ω
Absolute V _{MAX} ⁽⁵⁾	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin		_	1.2	_	_	1.2	_	_	1.2	
Absolute V _{MIN}	_	-0.4		_	-0.4		_	-0.4	_	_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	200	_	1600	mV
V _{ICM} (AC	Dedicated reference clock pin	1050/1000/900/850 (2)		1050/1000/900/850 ⁽²⁾ 1050/1000/900/850 ⁽²⁾ 1050/1000/900/850 ⁽²⁾		50 ⁽²⁾ 1050/1000/900/85		00/850 ⁽²⁾	mV		
coupled) ⁽³⁾	RX reference clock pin	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1				.85 ⁽⁴⁾	V				
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
	100 Hz	_	_	-70	_	_	-70	_	_	-70	dBc/Hz
Transmitter	1 kHz	_	_	-90	_	_	-90	_	_	-90	dBc/Hz
REFCLK Phase Noise	10 kHz		_	-100	_	_	-100	_	_	-100	dBc/Hz
(622 MHz) ⁽²⁰⁾	100 kHz	_	_	-110	_	_	-110	_	_	-110	dBc/Hz
	≥1 MHz	_	_	-120		_	-120		_	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (17)	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	_	_	3	ps (rms)
R _{REF} (19)	_	_	1800 ±1%	_	_	1800 ±1%	_	_	180 0 ±1%	_	Ω
Transceiver Clock	<u> </u>			_			_				
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

Page 22 Switching Characteristics

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 5 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	sceive Grade	r Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0		0	_	_	0		_	0	_	dB
	DC Gain Setting = 1		2	_	_	2		_	2	_	dB
Programmable DC gain	DC Gain Setting = 2		4	_	_	4	_	_	4	_	dB
	DC Gain Setting = 3	_	6	_	_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8	_	_	8	_	_	8	_	dB
Transmitter											
Supported I/O Standards	_				-	1.4-V an	ıd 1.5-V PC	ML			
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
	85- Ω setting		85 ± 20%	_	_	85 ± 20%	_	_	85 ± 20%	_	Ω
Differential on-	100-Ω setting		100 ± 20%	_	_	100 ± 20%	_	_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%	_	_	120 ± 20%	_	_	120 ± 20%	_	Ω
	150-Ω setting		150 ± 20%	_	_	150 ± 20%	_	_	150 ± 20%	_	Ω
V _{OCM} (AC coupled)	0.65-V setting	_	650	_	_	650	_	_	650	_	mV
V _{OCM} (DC coupled)	_		650	_	_	650	_	_	650	_	mV
Rise time (7)	20% to 80%	30	_	160	30	_	160	30	_	160	ps
Fall time ⁽⁷⁾	80% to 20%	30	_	160	30	_	160	30		160	ps
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps	_	_	15	_	_	15	_	_	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	_	_	120	_	_	120	_	_	120	ps

Switching Characteristics Page 23

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 6 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed e 1	Trar	sceive Grade	r Speed 2	Tran	sceive Grade	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode	ı	ı	500	_	ı	500	_	_	500	ps
CMU PLL											
Supported Data Range	_	600	_	12500	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_	_	μs
t _{pll_lock} (16)	_	_	_	10	_	_	10	_	_	10	μs
ATX PLL											
	VCO post-divider L=2	8000	_	14100	8000	_	12500	8000	_	8500/ 10312.5 (24)	Mbps
Currented Date	L=4	4000	_	7050	4000	_	6600	4000		6600	Mbps
Supported Data Rate Range	L=8	2000	_	3525	2000	_	3300	2000	_	3300	Mbps
Ç	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	1000	_	1762.5	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_	_	μs
t _{pll_lock} (16)	_			10	_		10	_		10	μs
fPLL											
Supported Data Range	_	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_		μs

Page 26 Switching Characteristics

Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Made (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode ⁽²⁾	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO		C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
	3	I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
	3	C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
	3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
		C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

Notes to Table 25:

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

⁽³⁾ The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

Page 34 Switching Characteristics

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) (1)

Symbol/ Description	Conditions		Transceiver Transceiver Speed Grade 2 Speed Grade 3					Unit
Description		Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs

Notes to Table 28:

- (1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the VCCR_GXB power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (6) Refer to Figure 6 for the GT channel DC gain curves.
- (7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.
- (9) t_{LTB} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (10) tLTD is time required for the receiver CDR to start recovering valid data after the rx is lockedtodata signal goes high.
- (11) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (12) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (13) tpll powerdown is the PLL powerdown minimum pulse width.
- (14) tpll lock is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (17) For ES devices, RREF is 2000 Ω ±1%.
- (18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (20) Refer to Figure 4.
- (21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (22) This supply follows VCCR_GXB for both GX and GT channels.
- (23) When you use fPLL as a TXPLL of the transceiver.

Page 38 Switching Characteristics

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

	Performance				
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	Unit	
Global and Regional Clock	717	650	580	MHz	
Periphery Clock	550	500	500	MHz	

Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

Switching Characteristics Page 39

PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range (-40° to 100° C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f _{IN}	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 ⁽¹⁾	MHz
INPFD	Input frequency to the PFD	5	_	325	MHz
FINPFD	Fractional Input clock frequency to the PFD	50	_	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f _{vco} ⁽⁹⁾	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	_	1300	MHz
EINDUTY	Input clock or external feedback clock input duty cycle	40	_	60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	_	_	717 (2)	MHz
Гоит	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 ⁽²⁾	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 ⁽²⁾	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f _{OUT_EXT}	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 (2)	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 ⁽²⁾	MHz
t _{оитриту}	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
FCOMP	External feedback clock compensation time	_		10	ns
DYCONFIGCLK	Dynamic Configuration Clock used for mgmt_clk and scanclk	_	_	100	MHz
Lock	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
DLOCK	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3		MHz
: CLBW	PLL closed-loop medium bandwidth		1.5		MHz
FOLDVV	PLL closed-loop high bandwidth (7)	_	4	_	MHz
PLL_PSERR	Accuracy of PLL phase shift		_	±50	ps
ARESET	Minimum pulse width on the areset signal	10	_	_	ns

Page 42 Switching Characteristics

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

		Peformance						
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit
		Modes us	ing Three	DSPs	•			
One complex 18 x 25	425	425	415	340	340	275	265	MHz
Modes using Four DSPs								
One complex 27 x 27	465	465	465	380	380	300	290	MHz

Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 1 of 2)

		Resources Used		Performance							
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, I2L	13, 13L, 13YY	14	Unit
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
MLAB	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
IVILAD	Simple dual-port, x16 depth (3)	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

Configuration Specification Page 55

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

Member			Active Serial (1)			Fast Passive Parallel (2)		
Variant	Variant Code		DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	D3	4	100	0.344	32	100	0.043	
	D4	4	100	0.534	32	100	0.067	
GS		4	100	0.344	32	100	0.043	
us	D5	4	100	0.534	32	100	0.067	
	D6	4	100	0.741	32	100	0.093	
	D8	4	100	0.741	32	100	0.093	
E	_ E9	4	100	0.857	32	100	0.107	
_	EB	4	100	0.857	32	100	0.107	

Notes to Table 48:

Fast Passive Parallel Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[] ratio for each combination.

Table 49. DCLK-to-DATA[] Ratio (1) (Part 1 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×8	Disabled	Enabled	1
IFF X0	Enabled	Disabled	2
	Enabled	Enabled	2
	Disabled	Disabled	1
EDD v16	Disabled	Enabled	2
FPP ×16	Enabled	Disabled	4
	Enabled	Enabled	4

⁽¹⁾ DCLK frequency of 100 MHz using external CLKUSR.

⁽²⁾ Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Page 56 Configuration Specification

Table 49. DCLK-to-DATA[] Ratio (1) (Part 2 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

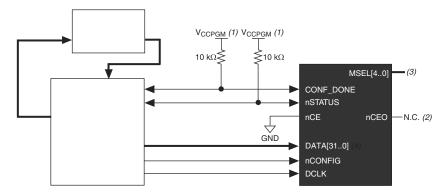
(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio -1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM}.
- (2) You can leave the nceo pin unconnected or use it as a user I/O pin when it does not feed another device's nce pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP $\times 8$, use DATA [7..0]. If you use FPP $\times 16$, use DATA [15..0].

Configuration Specification Page 59

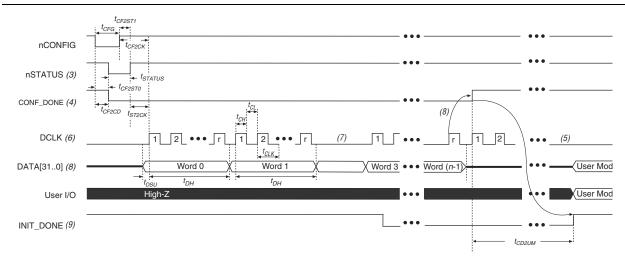


Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)

Notes to Figure 13:

- (1) Use this timing waveform and parameters when the DCLK-to-DATA [] ratio is >1. To find out the DCLK-to-DATA [] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nconfig, nstatus, and conf_done are at logic high levels. When nconfig is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA [31..0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Page 60 Configuration Specification

Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1 $^{(1)}$

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nconfig low to conf_done low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nconfig high to nstatus high	_	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nconfig high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} (5)	nstatus high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	N-1/f _{DCLK} ⁽⁵⁾	_	S
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	_	100	MHz
t _R	Input rise time	_	40	ns
t _F	Input fall time	_	40	ns
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_

Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nconfig or nstatus low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the DCLK-to-DATA ratio and f_{DCLK} is the DCLK frequency the system is operating.
- (6) If nstatus is monitored, follow the t_{status} specification. If nstatus is not monitored, follow the t_{cfack} specification.

Configuration Specification Page 61

Active Serial Configuration Timing

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52. DCLK Frequency Specification in the AS Configuration Scheme (1), (2)

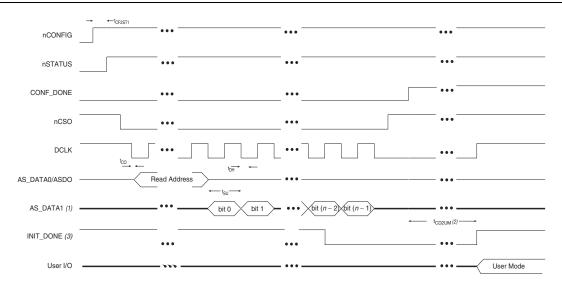
Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

Notes to Table 52:

- This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.
- (2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.

Figure 14. AS Configuration Timing



Notes to Figure 14:

- (1) If you are using AS ×4 mode, this signal represents the AS_DATA [3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or ${\tt CLKUSR}$ pin.
- (3) After the option bit to enable the $INIT_DONE$ pin is configured into the device, the $INIT_DONE$ goes low.

Table 53 lists the timing parameters for AS $\times 1$ and AS $\times 4$ configurations in Stratix V devices.

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CO}	DCLK falling edge to AS_DATAO/ASDO output	_	2	ns
t _{SU}	Data setup time before falling edge on DCLK	1.5	_	ns
t _H	Data hold time after falling edge on DCLK	0	_	ns

Page 64 I/O Timing

Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

Table 56. Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit
t _{RU_nCONFIG} (1)	250	_	ns
t _{RU_nRSTIMER} (2)	250	_	ns

Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

Table 57. 12.5-MHz Internal Oscillator Specifications

Minimum	Typical	Maximum	Units
5.3	7.9	12.5	MHz

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Parameter	Available Settings	Min Offset	Fast Model		Slow Model							
			Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

Page 68 Glossary

Table 60. Glossary (Part 4 of 4)

Letter	Subject	Definitions			
	V _{CM(DC)}	DC common mode input voltage.			
	V _{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.			
	V _{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.			
	V _{DIF(AC)}	AC differential input voltage—Minimum AC input differential voltage required for switching.			
	V _{DIF(DC)}	DC differential input voltage— Minimum DC input differential voltage required for switching.			
	V _{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.			
	V _{IH(AC)}	High-level AC input voltage			
	V _{IH(DC)}	High-level DC input voltage			
V	V _{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.			
	V _{IL(AC)}	Low-level AC input voltage			
	V _{IL(DC)}	Low-level DC input voltage			
	V _{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.			
	V _{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.			
	V _{SWING}	Differential input voltage			
	V _X	Input differential cross point voltage			
	V _{OX}	Output differential cross point voltage			
W	W	High-speed I/O block—clock boost factor			
Χ					
Υ		_			
Z					

Document Revision History Page 71

Table 61. Document Revision History (Part 3 of 3)

Date	Version	Changes		
		■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 60		
May 2013	2.7	■ Added Table 24, Table 48		
		■ Updated Figure 9, Figure 10, Figure 11, Figure 12		
February 2013	2.6	■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 35, Table 46		
		■ Updated "Maximum Allowed Overshoot and Undershoot Voltage"		
		■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 27, Table 30, Table 32, Table 35		
		■ Added Table 33		
		■ Added "Fast Passive Parallel Configuration Timing"		
D	0.5	■ Added "Active Serial Configuration Timing"		
December 2012	2.5	■ Added "Passive Serial Configuration Timing"		
		■ Added "Remote System Upgrades"		
		■ Added "User Watchdog Internal Circuitry Timing Specification"		
		■ Added "Initialization"		
		■ Added "Raw Binary File Size"		
		■ Added Figure 1, Figure 2, and Figure 3.		
June 2012	2.4	■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 27, Table 29, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 41, Table 43, Table 56, and Table 59.		
		Various edits throughout to fix bugs.		
		■ Changed title of document to Stratix V Device Datasheet.		
		■ Removed document from the Stratix V handbook and made it a separate document.		
February 2012	2.3	■ Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.		
December 2011	2.2	■ Added Table 2–31.		
December 2011	2.2	■ Updated Table 2–28 and Table 2–34.		
Nevember 0011	0.1	■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information about Stratix V GT devices.		
November 2011	2.1	■ Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.		
		■ Various edits throughout to fix SPRs.		
		■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2–23, and Table 2–24.		
May 2011	2.0	■ Updated the "DQ Logic Block and Memory Output Clock Jitter Specifications" title.		
		■ Chapter moved to Volume 1.		
		■ Minor text edits.		
	1.1	■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.		
December 2010		Converted chapter to the new template.		
		■ Minor text edits.		
July 2010	1.0	Initial release.		